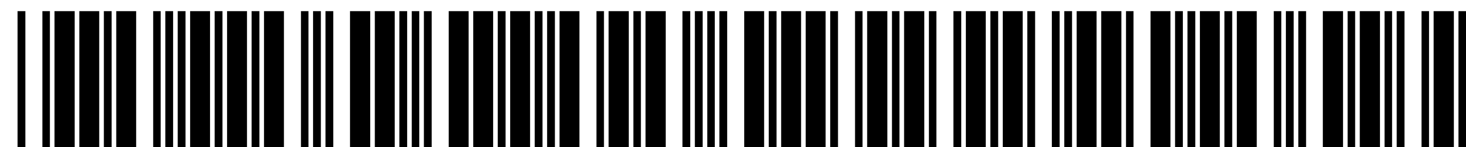

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(12) **Reissued Patent**
Inanami et al.

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(45) **Date of Reissued Patent: Nov. 9, 2021**

(54) **METHOD OF DESIGNING A TEMPLATE PATTERN, METHOD OF MANUFACTURING A TEMPLATE AND METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE**

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(73) Assignee: **Kioxia Corporation**, Tokyo (JP)

(21) Appl. No.: **14/741,889**

(22) Filed: **Jun. 17, 2015**

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Issued: **Jun. 18, 2013**
Appl. No.: **12/725,202**
Filed: **Mar. 16, 2010**

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G06F 30/398 (2020.01)
G06F 119/18 (2020.01)

(52) **U.S. Cl.**
CPC ***G06F 30/398*** (2020.01); *G06F 2119/18* (2020.01); *Y02P 90/02* (2015.11)

(58) **Field of Classification Search**
CPC . G06F 17/5081; G06F 2217/12; Y02P 90/265
See application file for complete search history.

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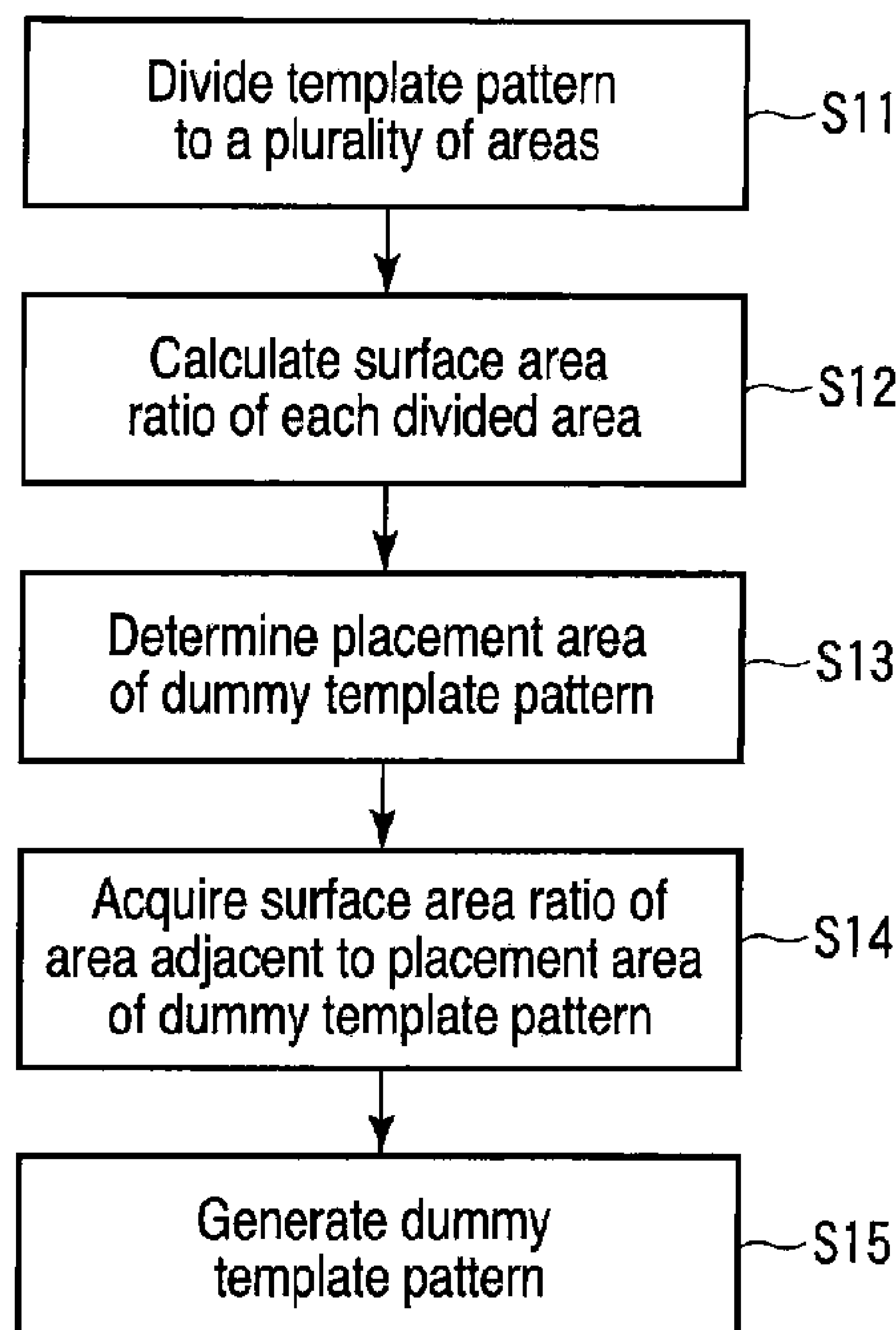
Primary Examiner — Luke S Wassum
(74) *Attorney, Agent, or Firm* — Finnegan, Henderson, Farabow, Garrett & Dunner L.L.P.

(57) **ABSTRACT**

A method of designing a template pattern used for imprint lithography, includes generating data of a dummy template pattern to be formed in a third area between first and second areas of a template based on data of a design pattern of the template, the data of the dummy template pattern being generated so that a third surface area ratio showing a ratio of a surface area of the third area to an area of the third area is set smaller than a first surface area ratio showing a ratio of a surface area of the first area to an area of the first area and larger than a second surface area ratio showing a ratio of a surface area of the second area to an area of the second area.

27 Claims, 10 Drawing Sheets



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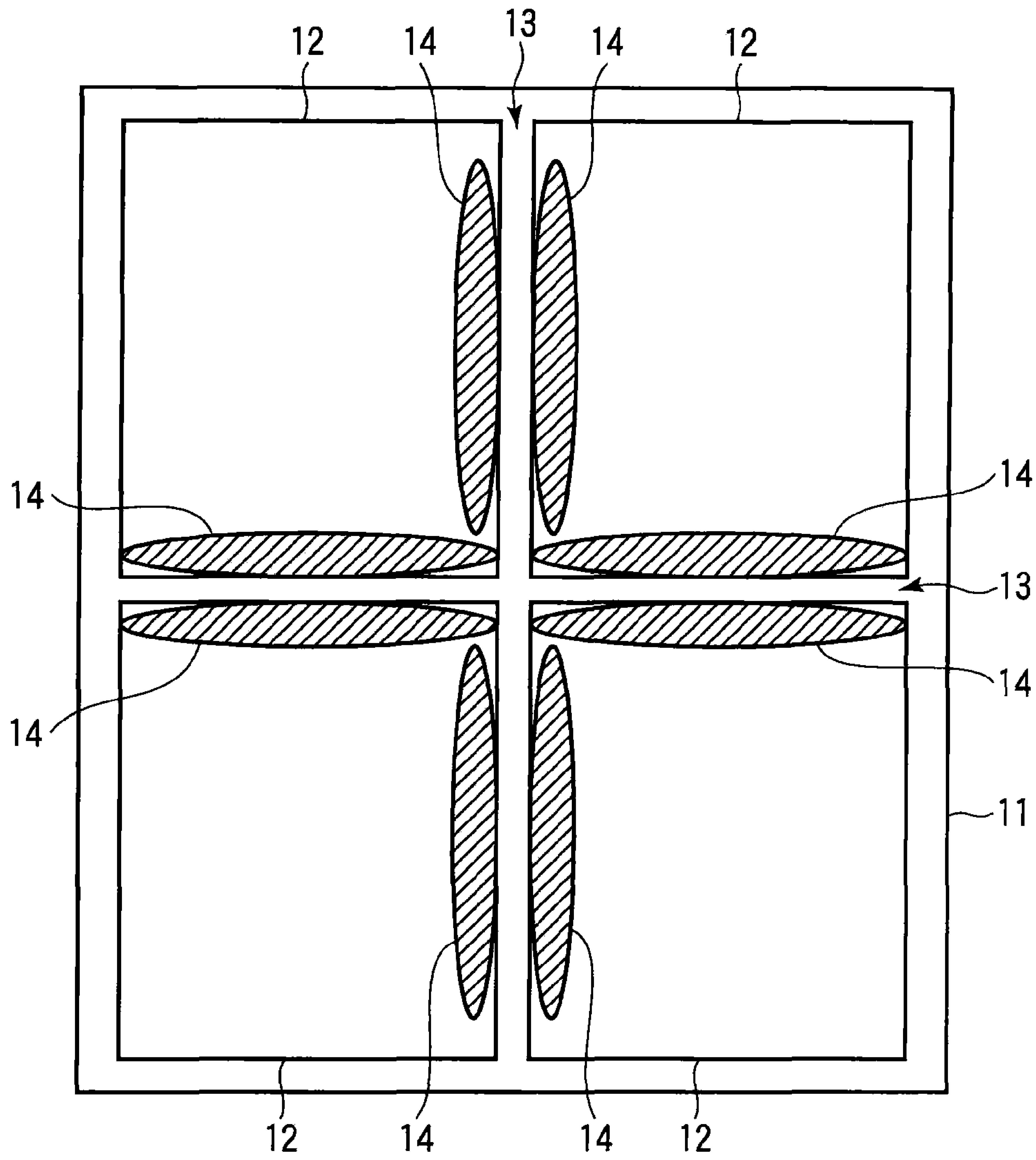


FIG. 1

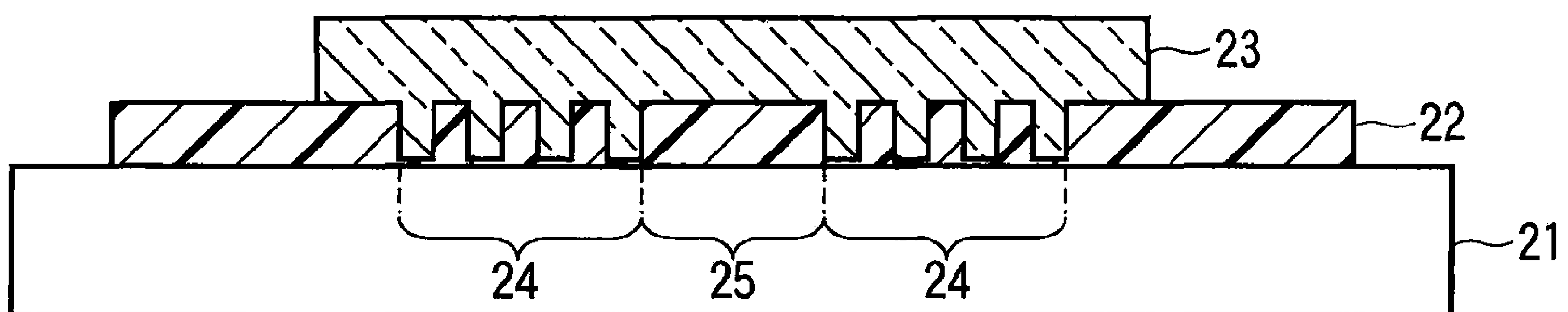


FIG. 2

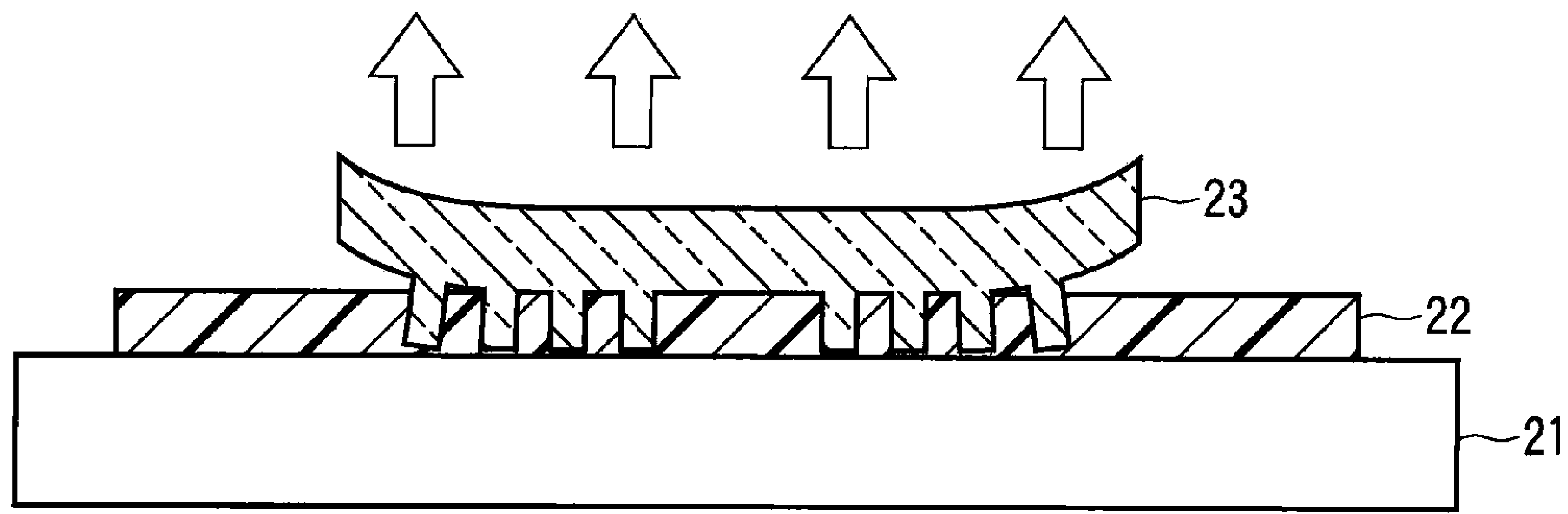


FIG. 3

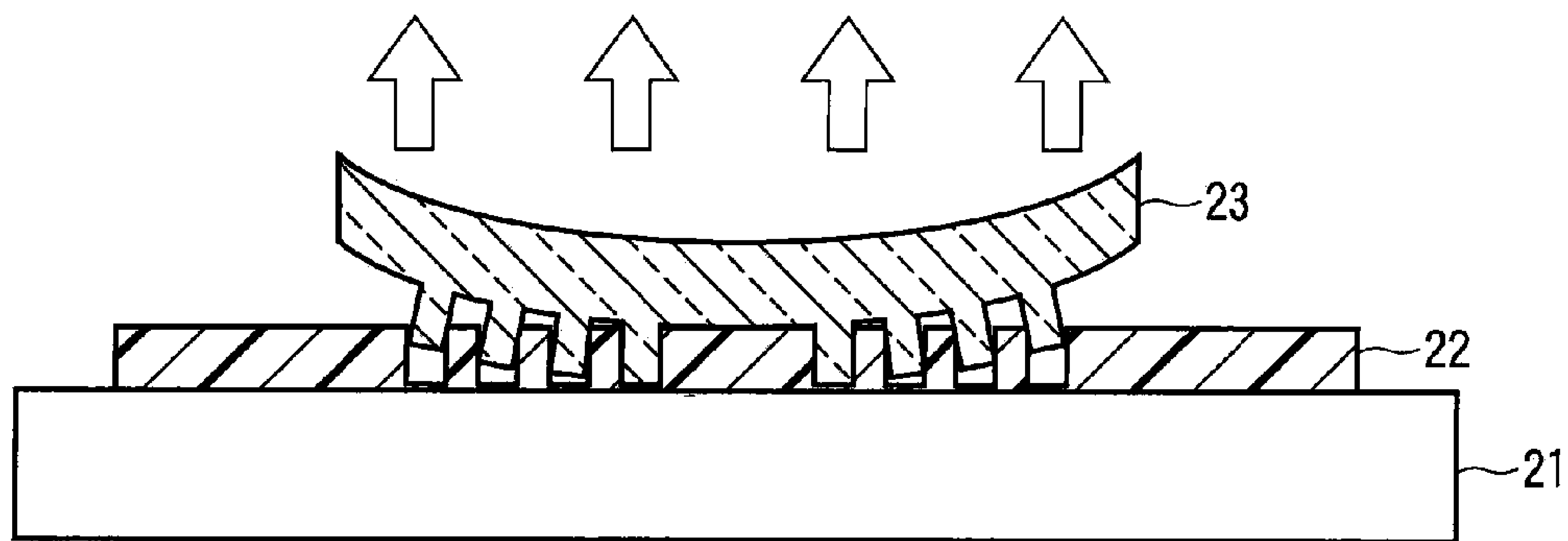


FIG. 4

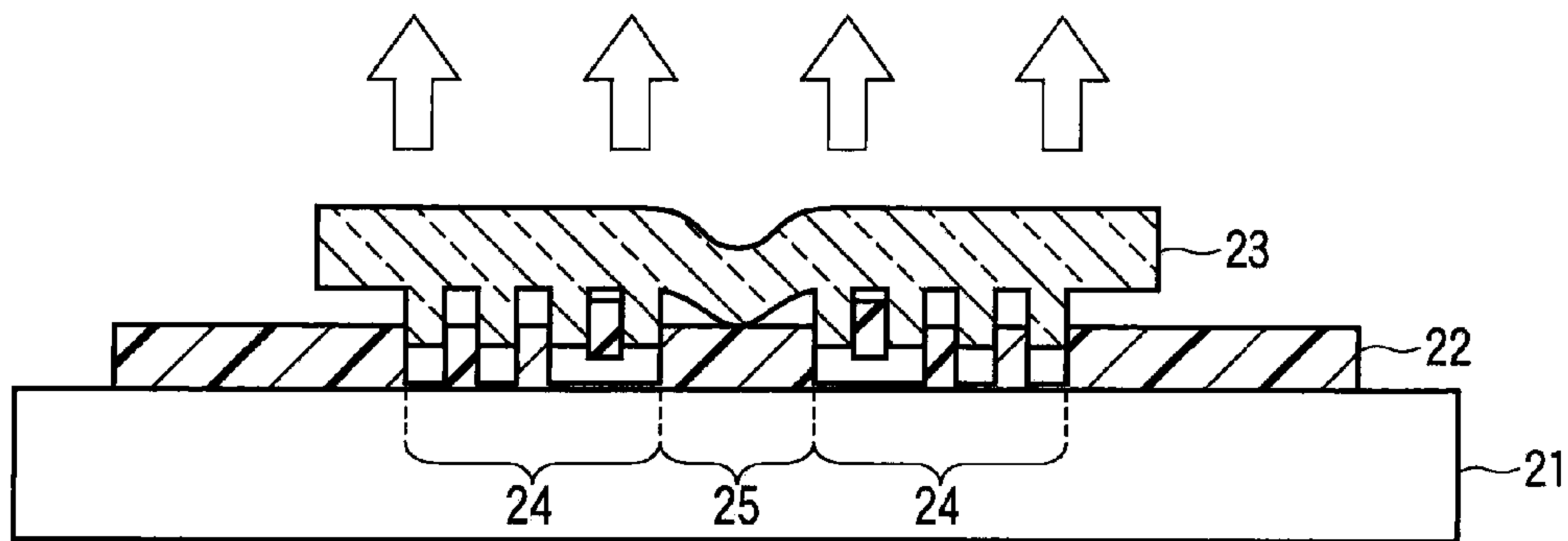


FIG. 5

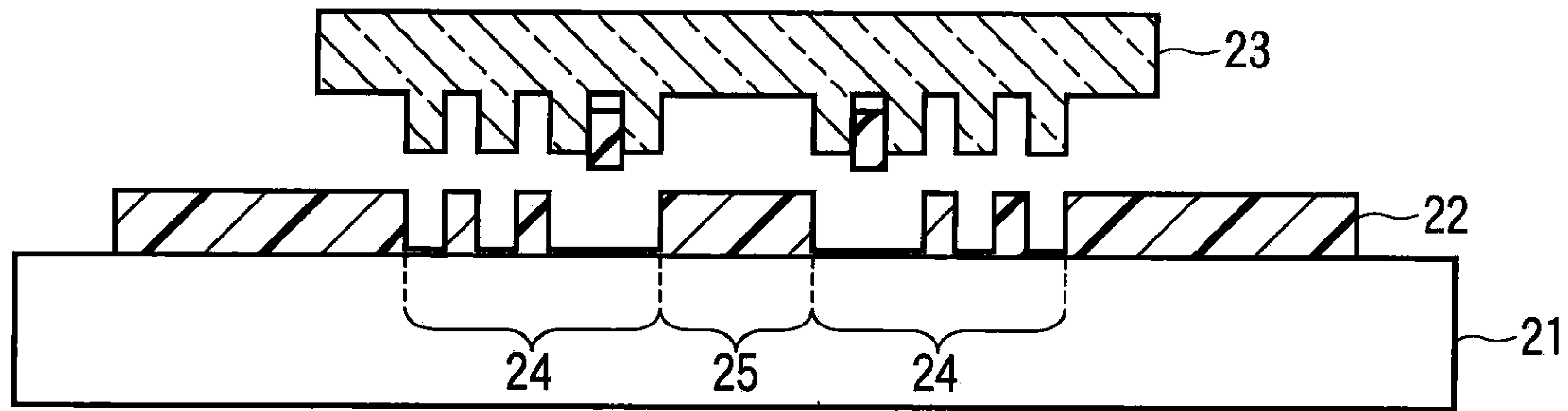


FIG. 6

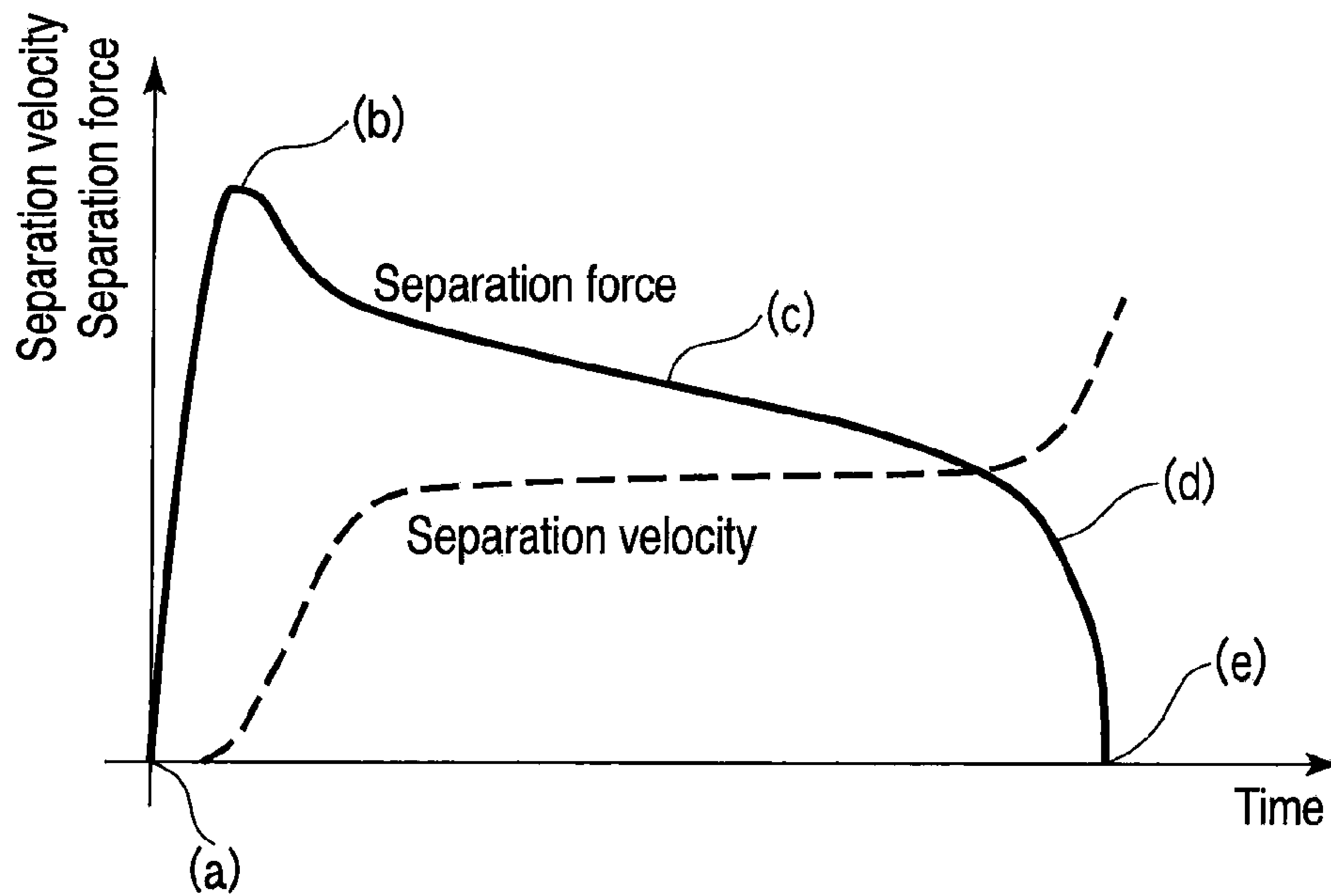


FIG. 7

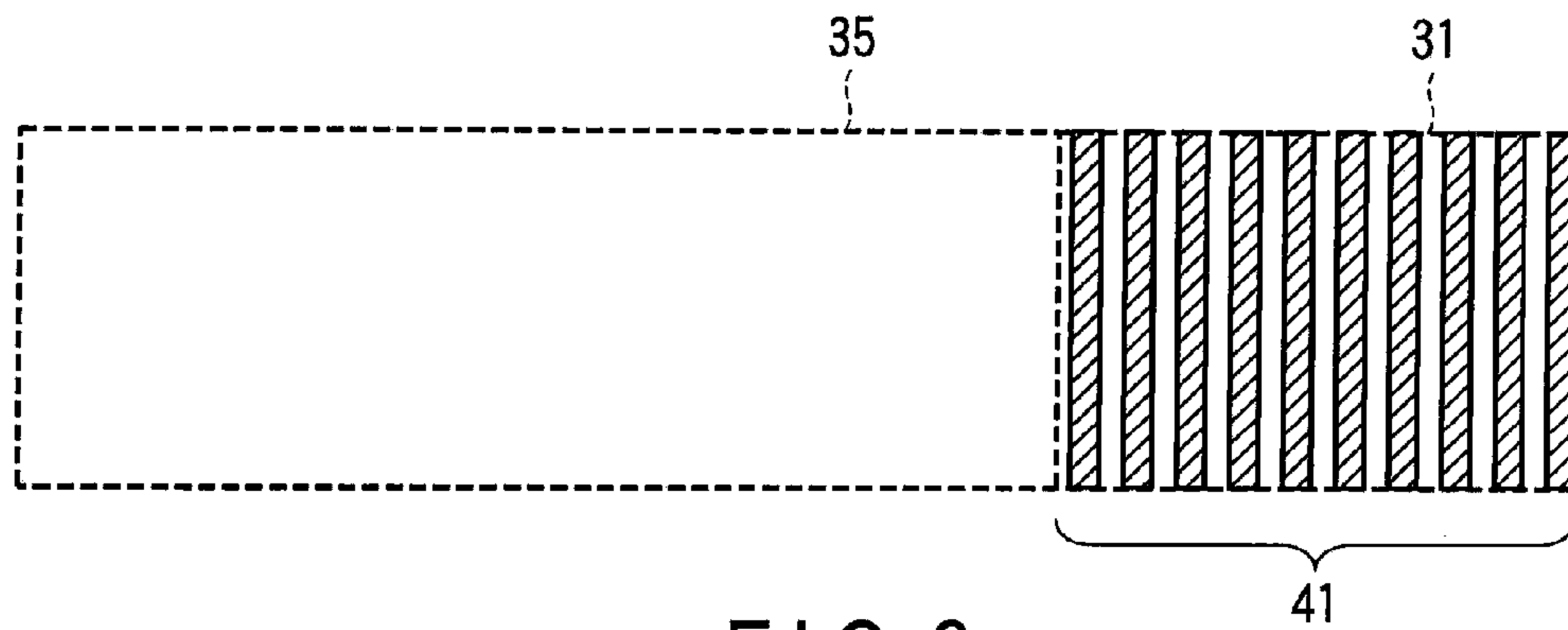


FIG.8

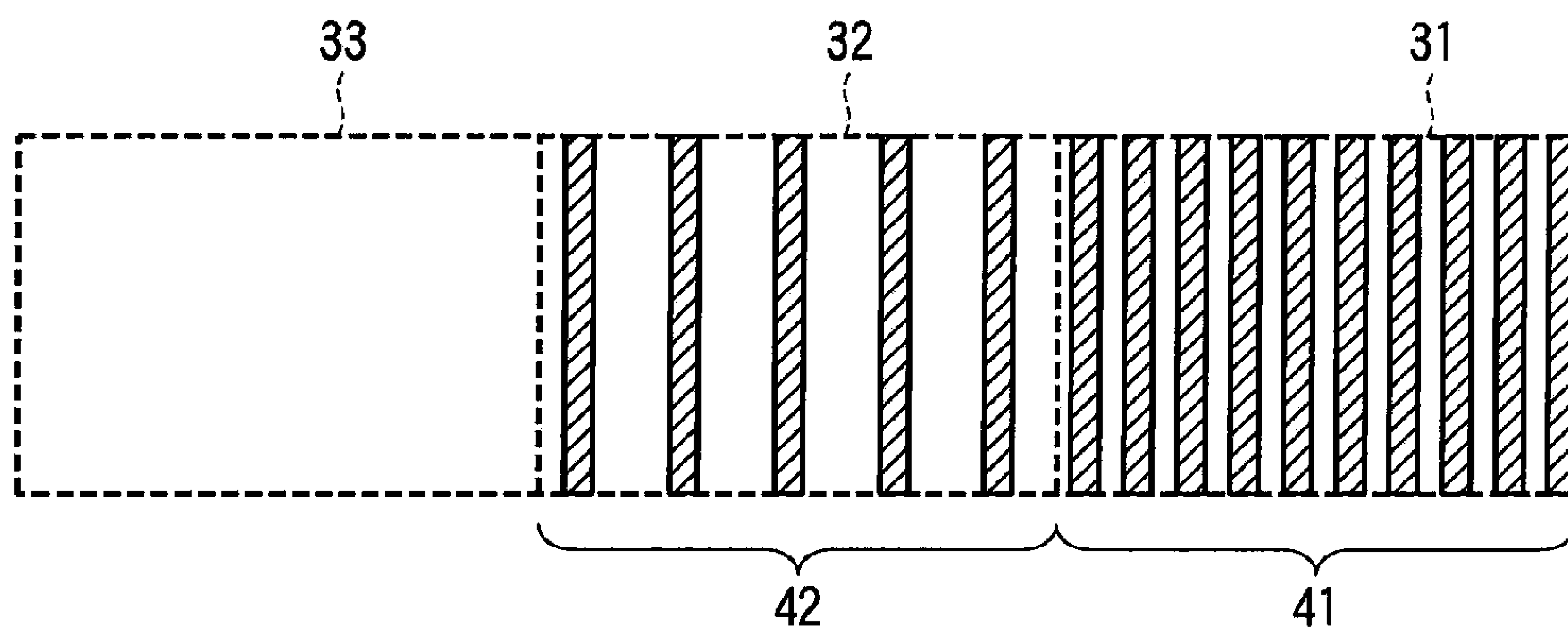


FIG.9

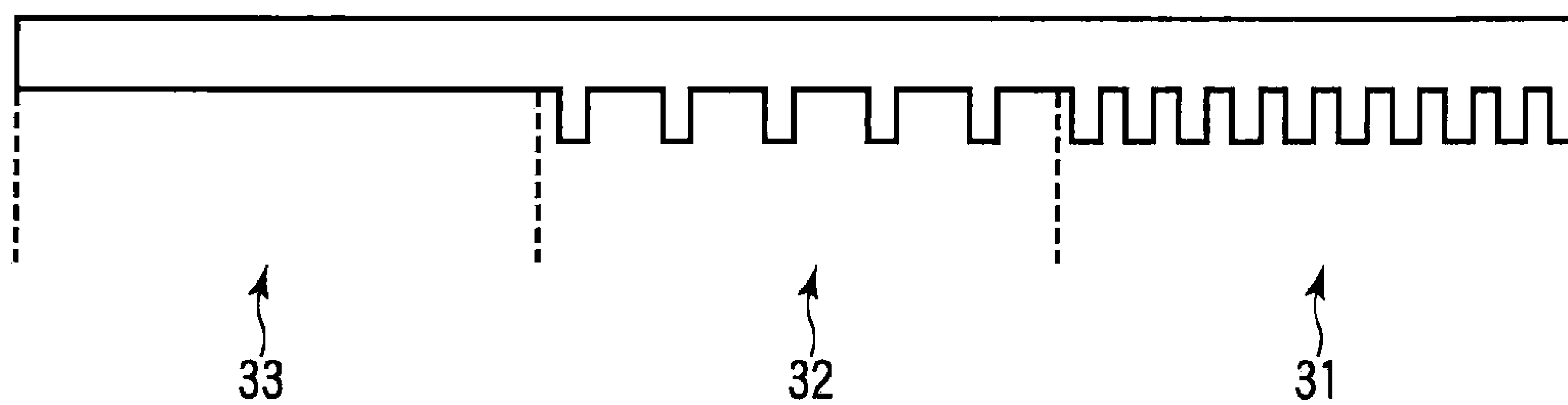
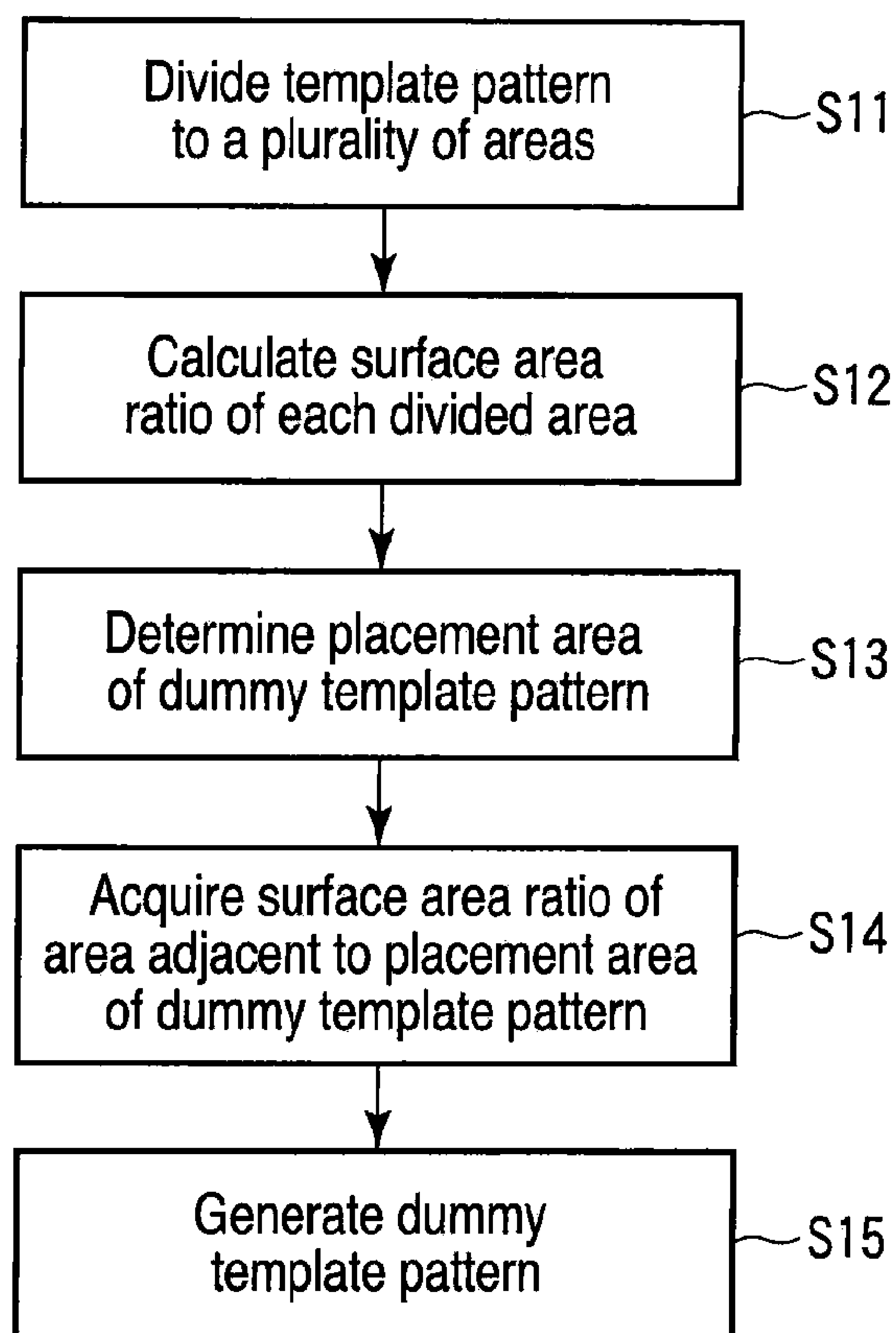
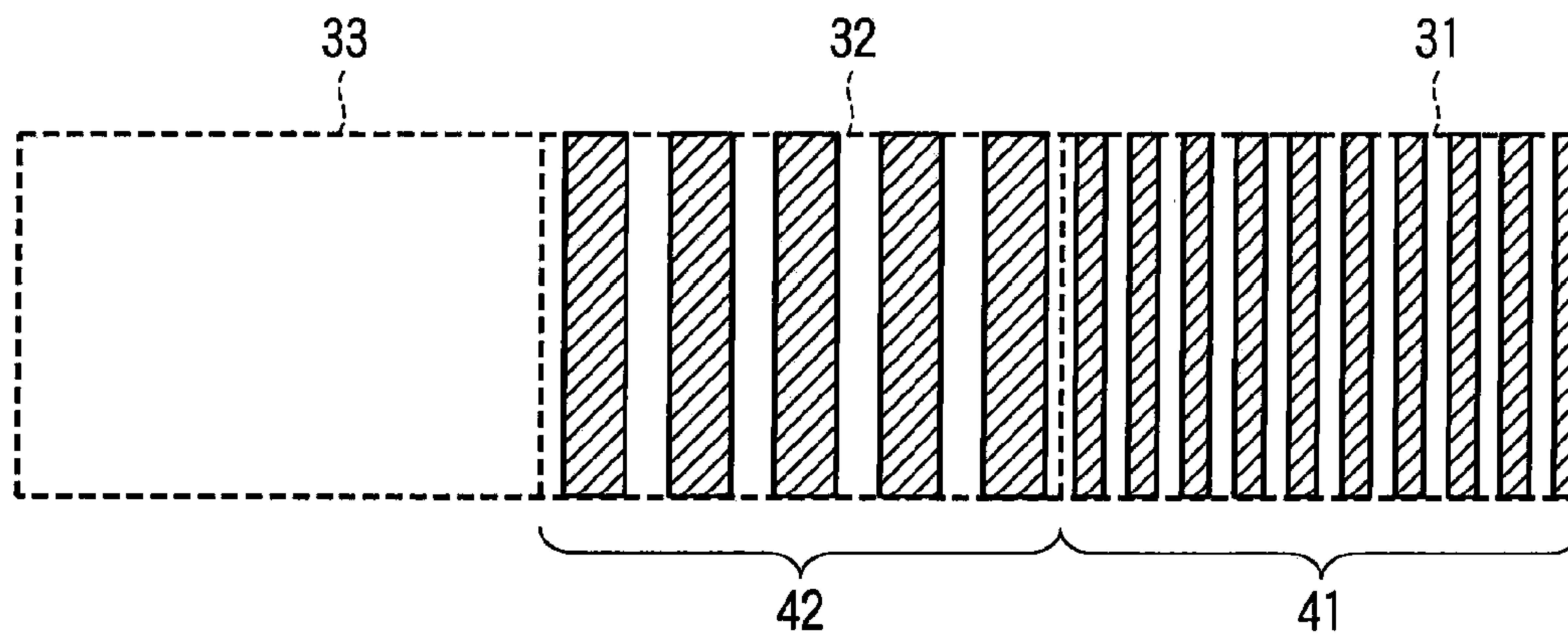


FIG.10



F I G. 11



F I G. 12

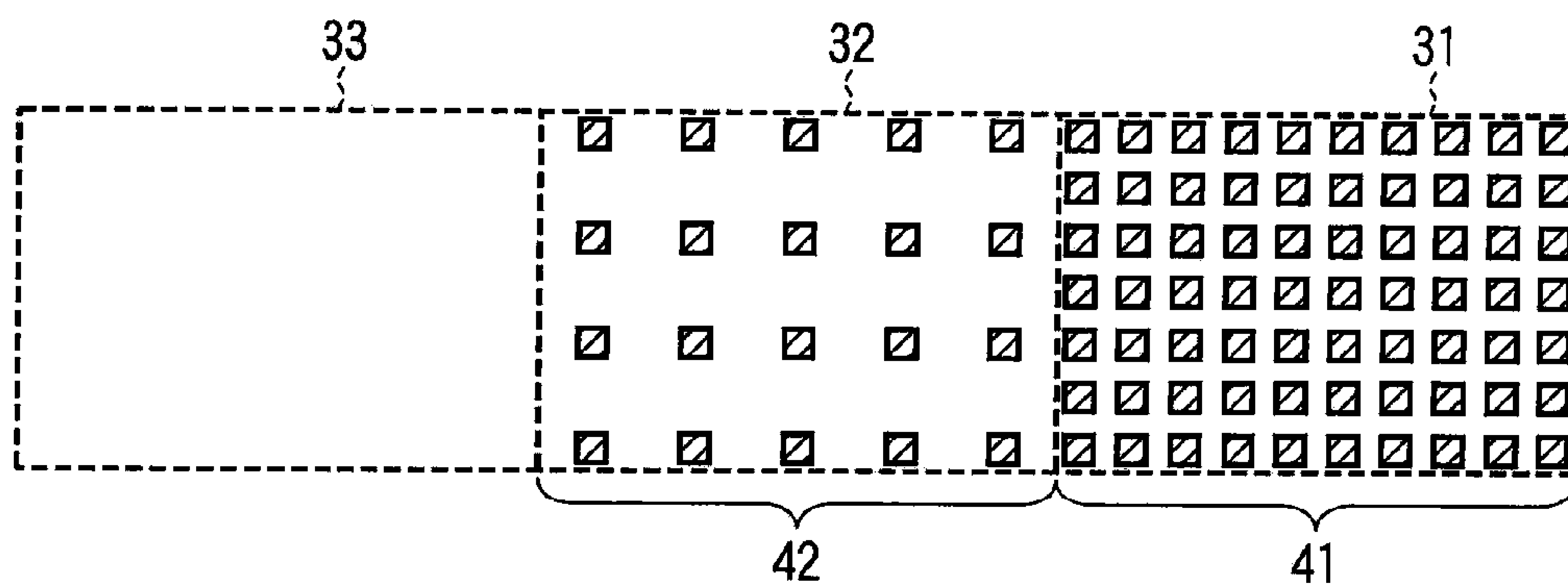


FIG. 13

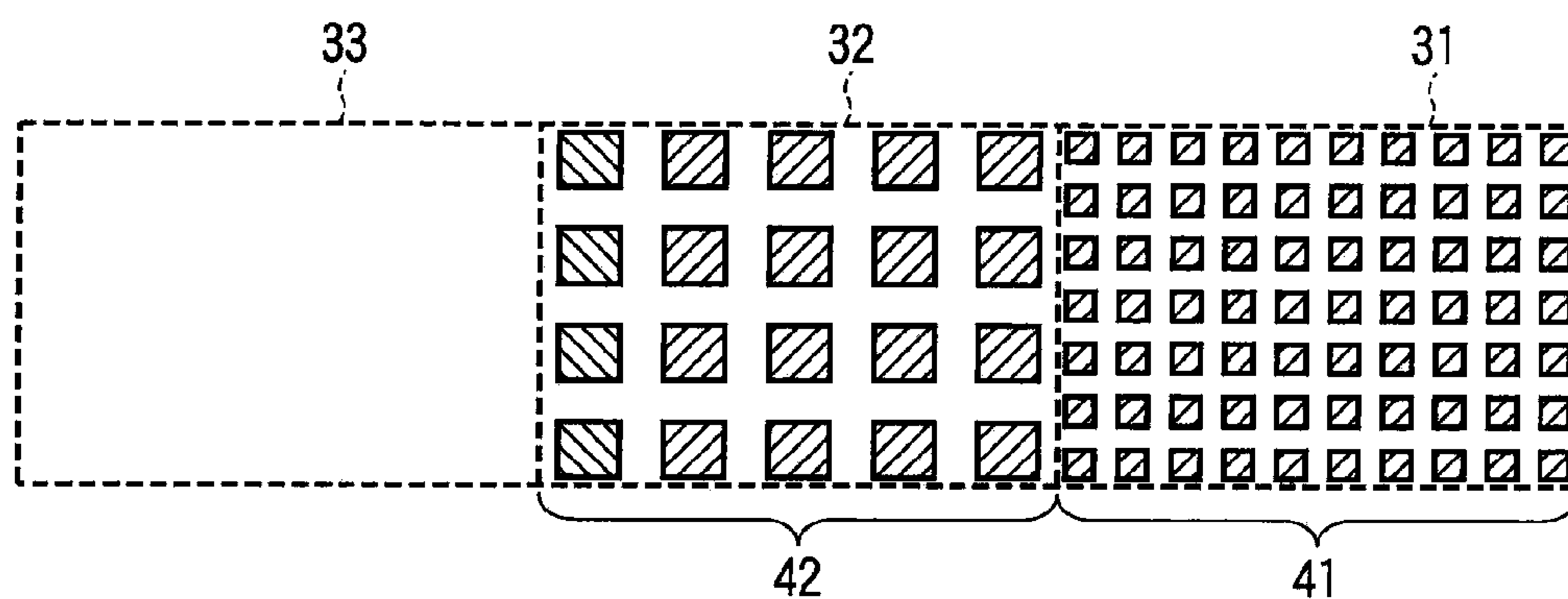


FIG. 14

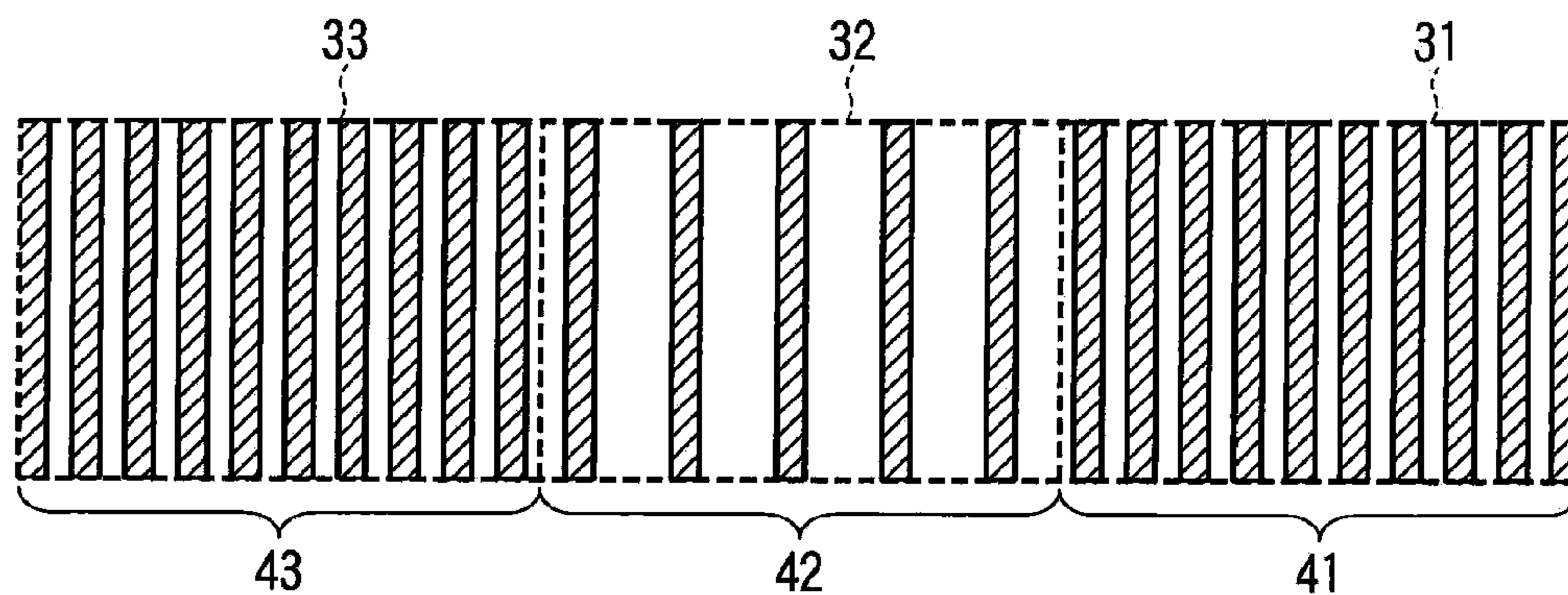
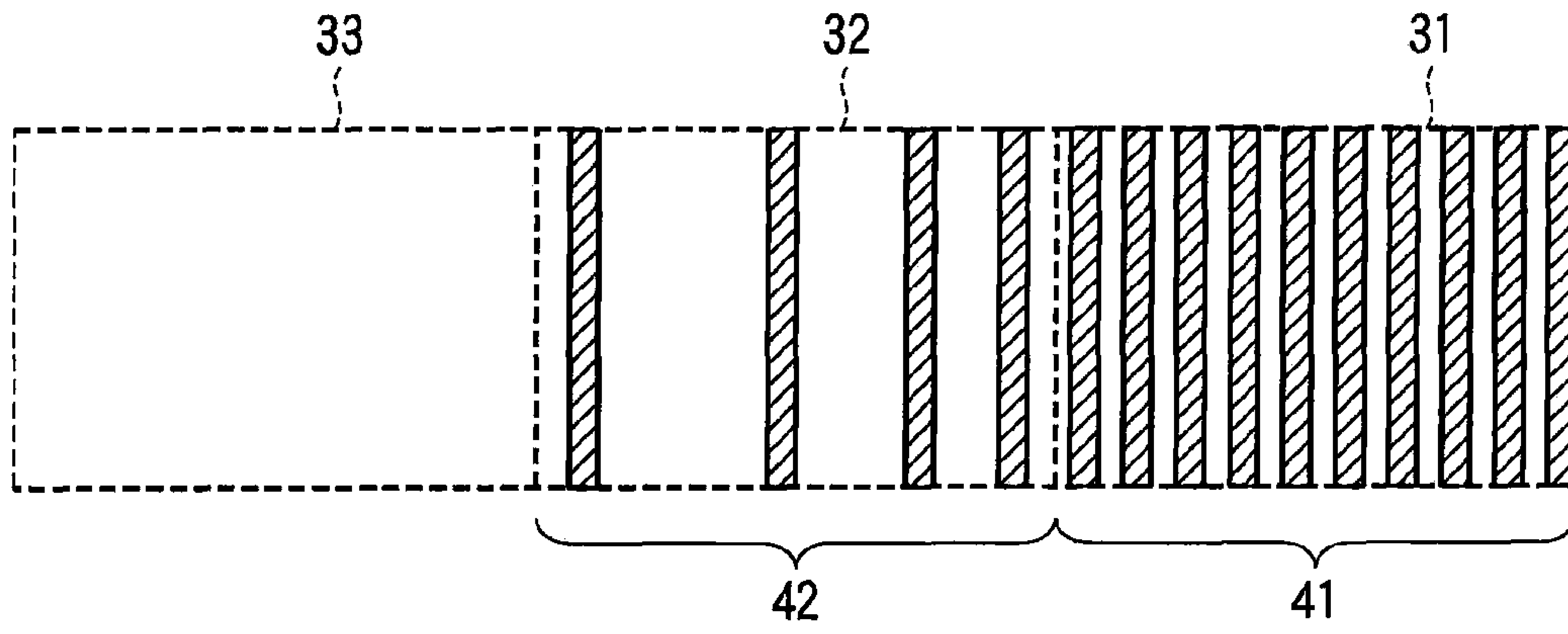
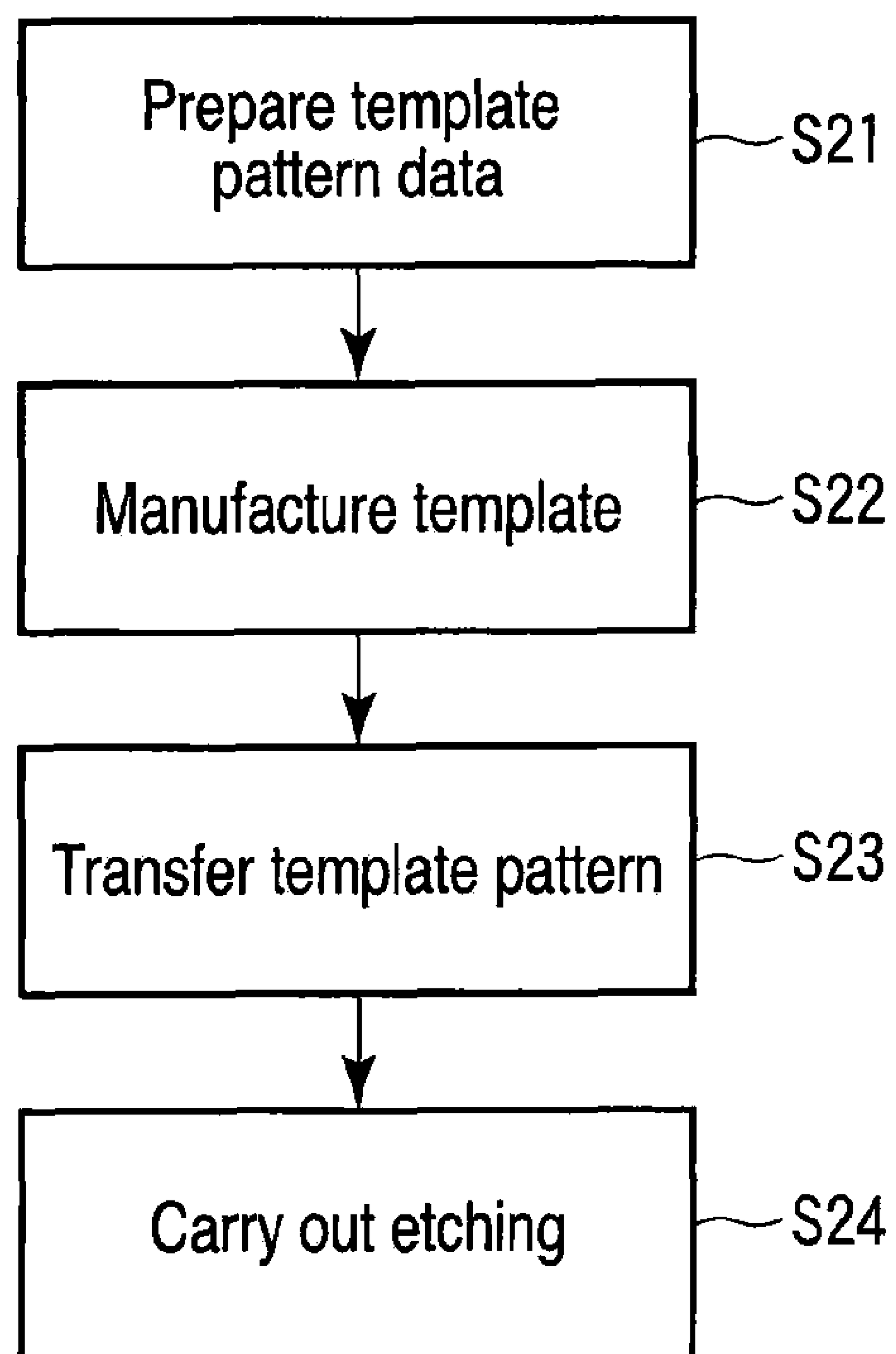


FIG. 15



F I G. 16



F I G. 17

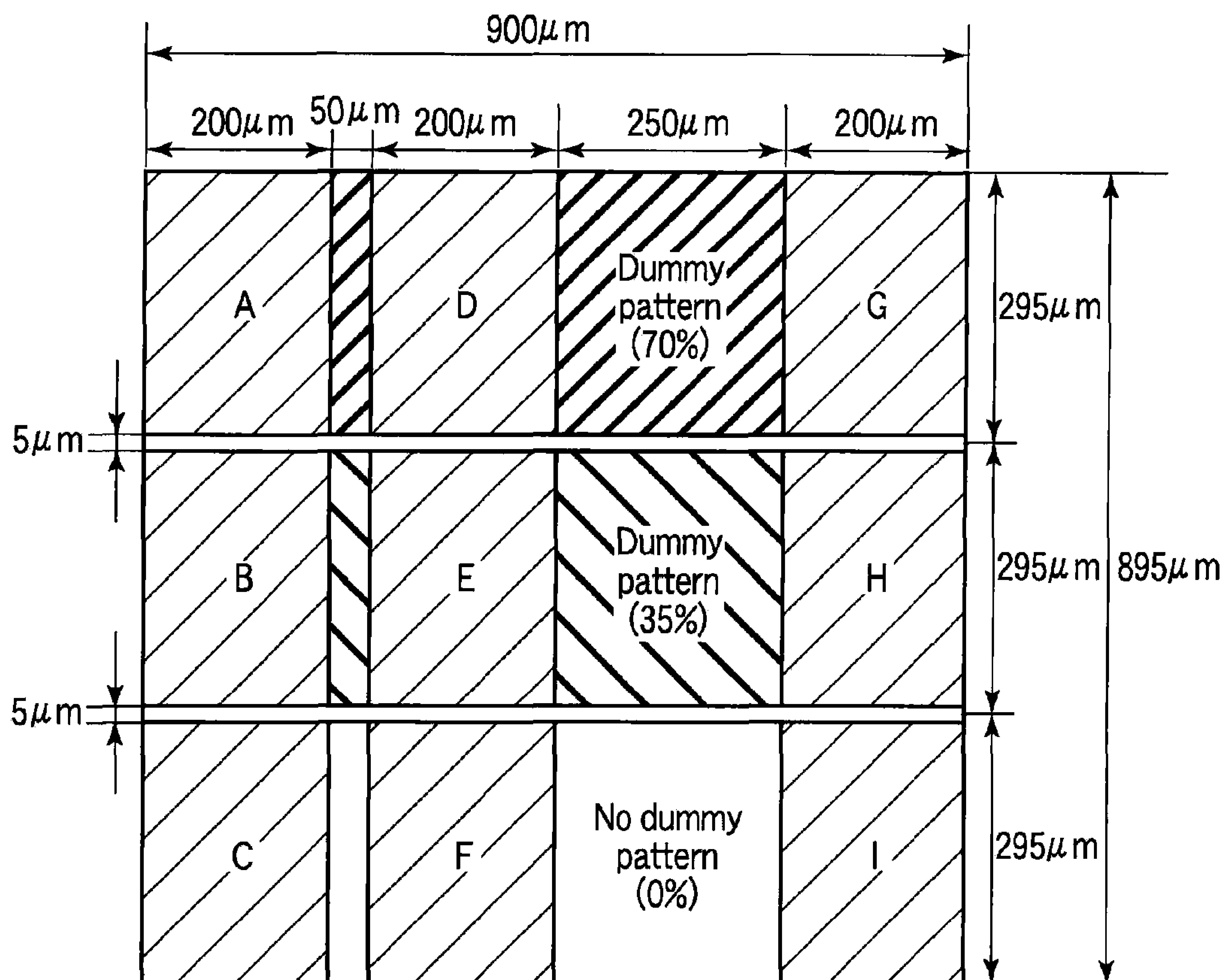


FIG. 18

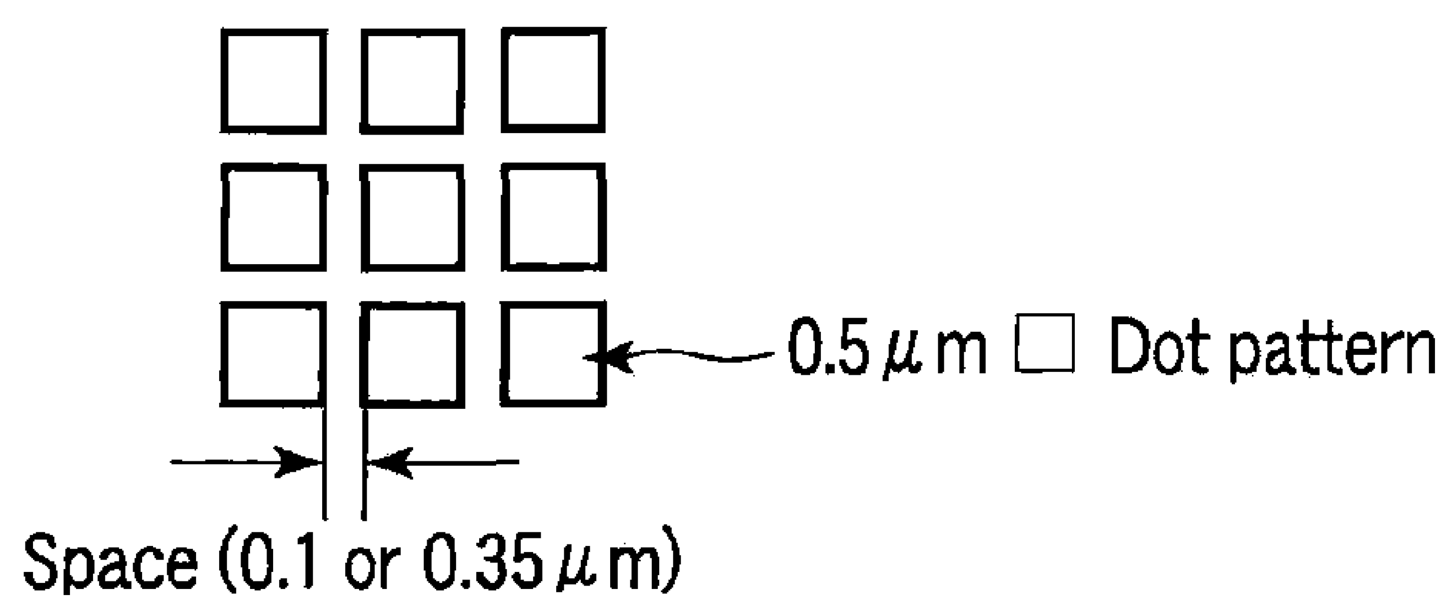


FIG. 19

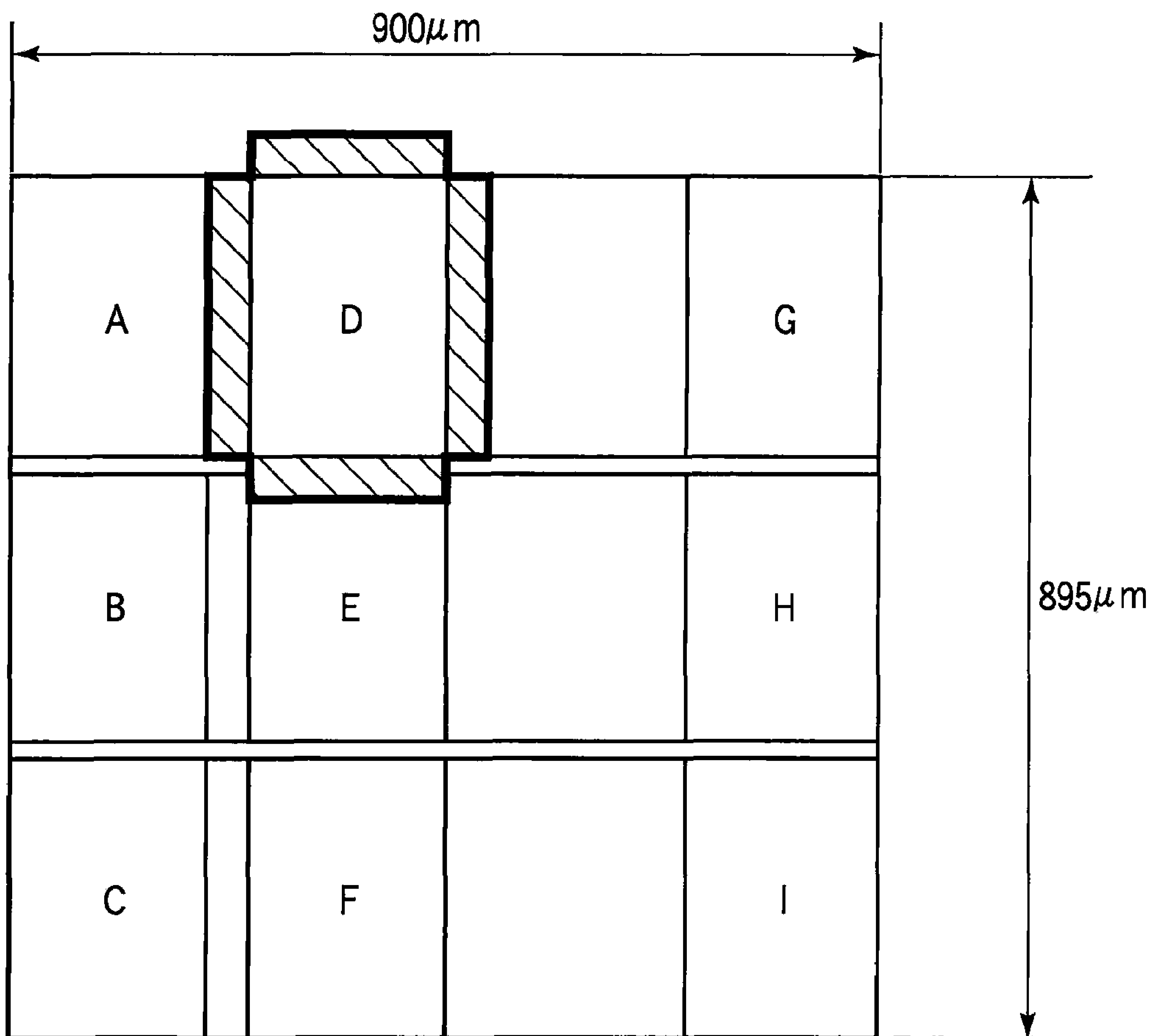


FIG. 20

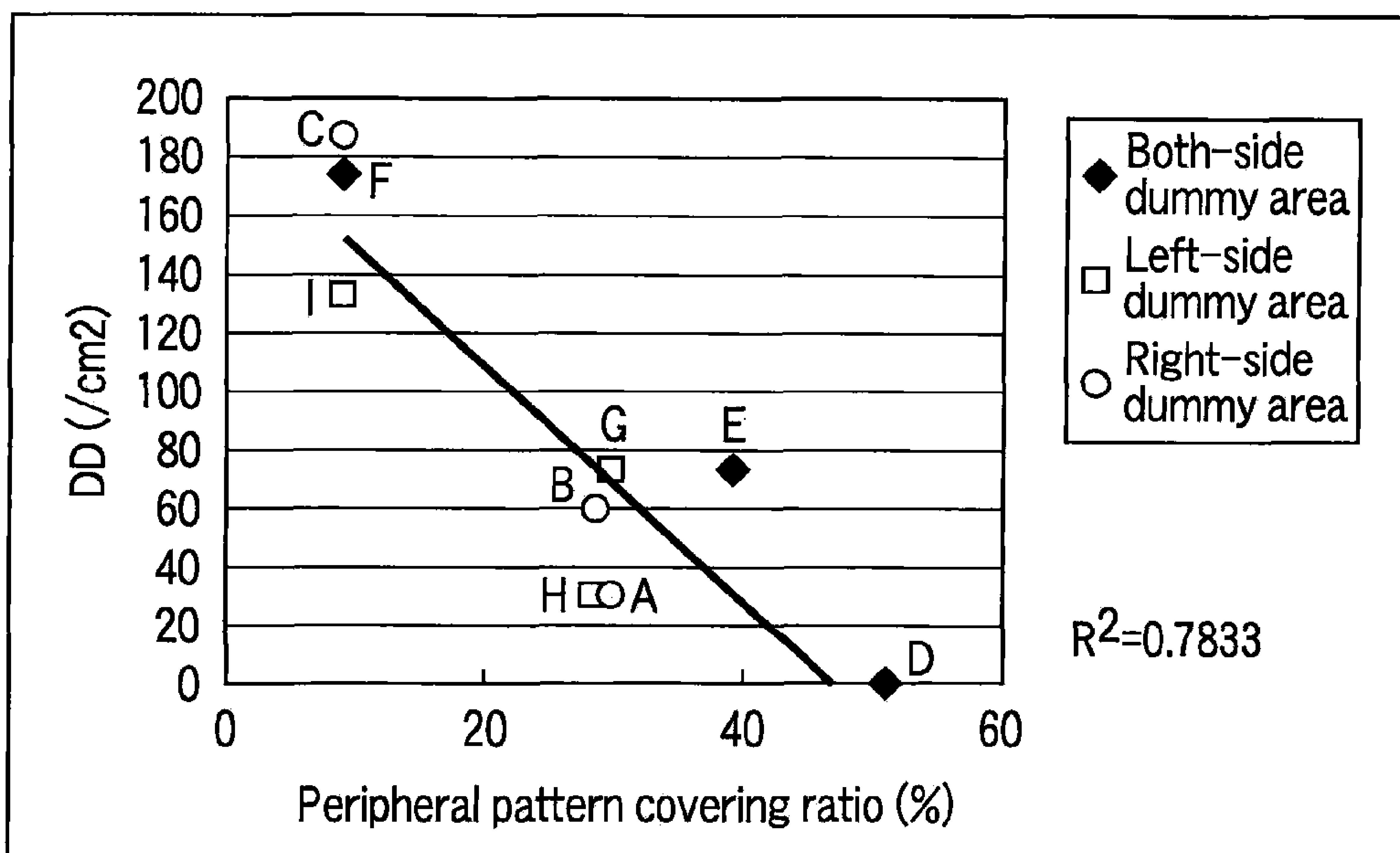


FIG. 21

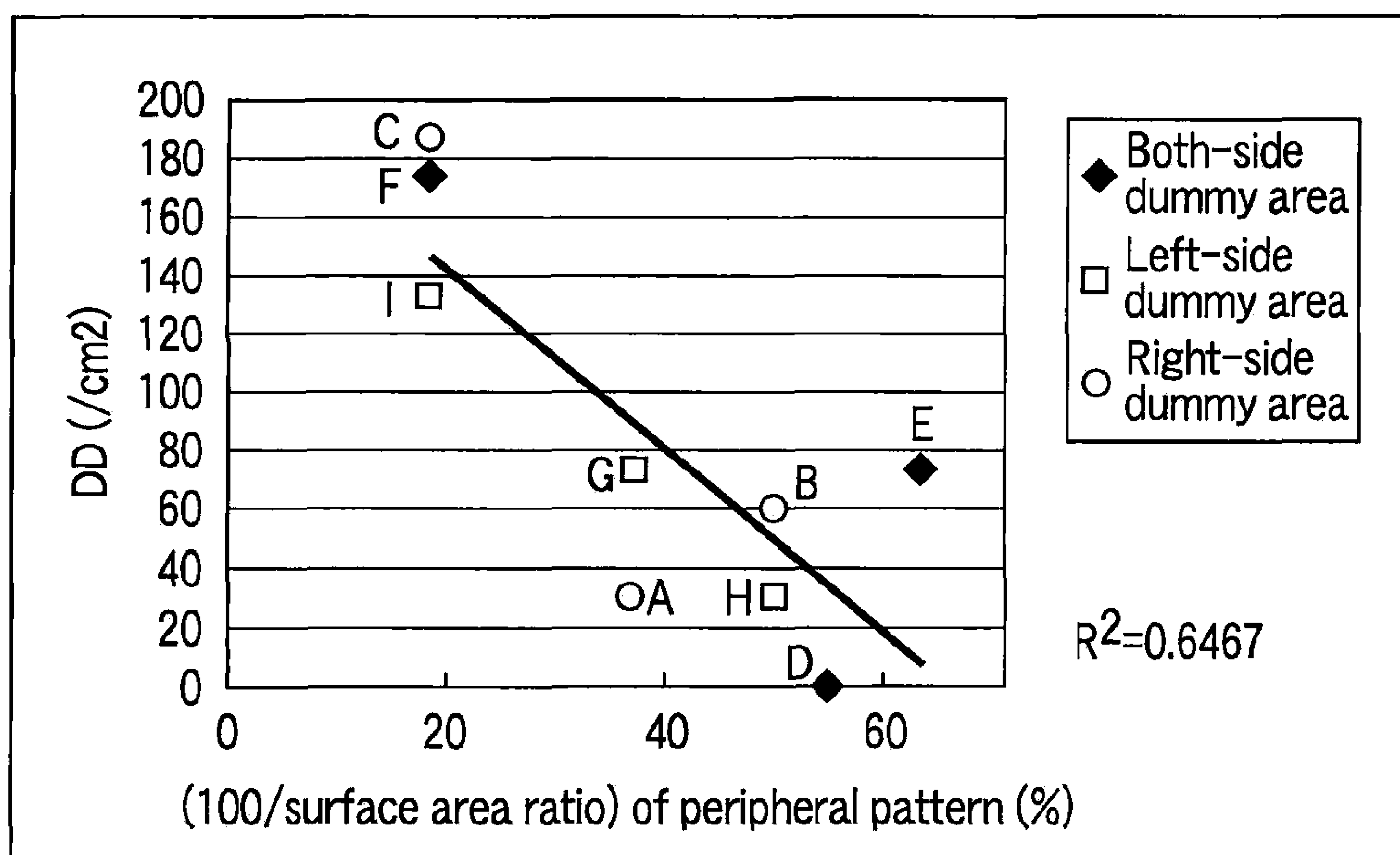


FIG. 22

METHOD OF DESIGNING A TEMPLATE PATTERN, METHOD OF MANUFACTURING A TEMPLATE AND METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE

Matter enclosed in heavy brackets [ ] appears in the original patent but forms no part of this reissue specification; matter printed in italics indicates the additions made by reissue; a claim printed with strikethrough indicates that the claim was canceled, disclaimed, or held invalid by a prior post-patent action or proceeding.

CROSS-REFERENCE TO RELATED APPLICATIONS

This application *is a reissue of U.S. Pat. No. 8,468,480, issued on Jun. 18, 2013, from U.S. patent application Ser. No. 12/725,202, which* is based upon and claims the benefit of priority from prior Japanese Patent Application No. 2009-068961, filed Mar. 19, 2009, the entire contents of which *applications* are incorporated herein by reference.

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention relates to a method of designing a template pattern, a method of manufacturing a template and a method of manufacturing a semiconductor device.

2. Description of the Related Art

Imprint lithography is proposed as a pattern transfer technique in a process of manufacturing a semiconductor device (e.g., see Jpn. Pat. Appln. KOKAI Publication No. 2006-303503). According to the imprint lithography, a template (mold) having a device pattern is in contact with an imprint material layer such as a resist so that the device pattern is transferred to the imprint material layer.

However, the imprint lithography has the following problem. Specifically, when a template is separated from an imprint material layer, a defect is generated in a pattern of the imprint material layer.

BRIEF SUMMARY OF THE INVENTION

According to a first aspect of the present invention, there is provided a method of designing a template pattern used for imprint lithography, comprising: generating data of a dummy template pattern to be formed in a third area between first and second areas of a template based on data of a design pattern of the template, the data of the dummy template pattern being generated so that a third surface area ratio showing a ratio of a surface area of the third area to an area of the third area is set smaller than a first surface area ratio showing a ratio of a surface area of the first area to an area of the first area and larger than a second surface area ratio showing a ratio of a surface area of the second area to an area of the second area.

According to a second aspect of the present invention, there is provided a method of manufacturing a template, comprising: forming a template pattern designed using the above method in a template substrate.

According to a third aspect of the present invention, there is provided a method of manufacturing a semiconductor device, comprising: transferring a pattern formed in the template manufactured using the above method to an imprint material layer on a substrate.

BRIEF DESCRIPTION OF THE SEVERAL VIEWS OF THE DRAWING

FIG. **1** is a view schematically showing a defect generated area;

FIG. **2** is a view schematically showing one process of a separation operation in imprint;

FIG. **3** is a view schematically showing one process of a separation operation in imprint;

FIG. **4** is a view schematically showing one process of a separation operation in imprint;

FIG. **5** is a view schematically showing one process of a separation operation in imprint;

FIG. **6** is a view schematically showing one process of a separation operation in imprint;

FIG. **7** is a graph showing a change of a separation force and a separation velocity in a separation operation;

FIG. **8** is a view to explain the basic principle of an embodiment of the present invention;

FIG. **9** is a view to explain the basic principle of an embodiment of the present invention;

FIG. **10** is a view to explain the basic principle of an embodiment of the present invention;

FIG. **11** is a flowchart to explain a method of designing a template pattern according to an embodiment of the present invention;

FIG. **12** is a view schematically showing a first modification example of an embodiment of the present invention;

FIG. **13** is a view schematically showing a second modification example of an embodiment of the present invention;

FIG. **14** is a view schematically showing a third modification example of an embodiment of the present invention;

FIG. **15** is a view schematically showing a fourth modification example of an embodiment of the present invention;

FIG. **16** is a view schematically showing a fifth modification example of an embodiment of the present invention;

FIG. **17** is a flowchart to explain a method of manufacturing a template and a method of manufacturing a semiconductor device according to an embodiment of the present invention;

FIG. **18** is a view schematically showing a template pattern used for verifying the effect obtained according to the method of an embodiment of the present invention;

FIG. **19** is a view showing a dummy pattern formed in a template shown in FIG. **18**;

FIG. **20** is a view showing a calculation area of a peripheral pattern covering ratio with respect to an evaluation pattern formed in a template shown in FIG. **18**;

FIG. **21** is a graph to explain the relationship between a peripheral pattern covering ratio and a defect density in a template shown in FIG. **18**; and

FIG. **22** is a graph to explain the relationship between a surface area ratio of a peripheral pattern and a defect density in a template shown in FIG. **18**.

DETAILED DESCRIPTION OF THE INVENTION

An embodiment of the present invention will be hereinafter described with reference to the accompanying drawings.

Knowledge obtained by inventors will be first explained below prior to the detailed explanation of an embodiment.

As already described, there is a problem that a defect is generated in a resist pattern when a template is separated from a resist layer (imprint material layer). Specifically, when a template is separated, a part of a resist pattern is torn

off by the template, and as a result, the torn-off resist remains in a recess portion of a template pattern. The generation of the foregoing defect is a big factor of reducing the yield in imprint lithography.

Inventors have detailedly investigated the foregoing defect generated portion. As a result, it can be found that a defect is generated in a specified area. FIG. **1** is a view schematically showing a defect generated area.

In FIG. **1**, a reference numeral **11** denotes a one-shot area, that is, an area where an imprint pattern is transferred by one-time imprint operation of one template. A reference numeral **12** denotes a chip area, that is, an LSI chip pattern formation area. Usually, the chip area **12** is provided with a high-density LSI pattern. A reference numeral **13** denotes an interchip area corresponding to a dicing area. A reference numeral **14** denotes the foregoing defect generated area.

As shown in FIG. **1**, it can be seen that the defect generated area **14** collectively distributes near the end portions of the chip area. Hereinafter, the generation mechanism of the foregoing defect will be described.

FIGS. **2** to **6** are views schematically showing a separation operation in imprint. The generation mechanism of the defect will be explained below with reference to FIGS. **2** to **6**.

As shown in FIG. **2**, a template **23** is in contact with a resist layer (imprint material layer) **22** on a substrate (wafer) **21**. Thereafter, light (ultraviolet (UV) light) is irradiated to the resist layer **22** or the resist layer **22** is heated so that the resist layer **22** is hardened. In this way, a template pattern formed in the template **23** is transferred to the resist layer **22**. In FIG. **2**, a reference numeral **24** denotes a chip area, and **25** denotes an interchip area.

As illustrated in FIG. **3**, the template **23** is left up so that a separation operation is started. A contact area of a pattern formed surface of the template **23** with the resist layer **22** is very large; for this reason, a considerably strong adhesion force acts between the template **23** and the resist layer **22**. Resulting from the foregoing factor, a separation operation of the template **23** is started from a place easy to peel off. Specifically, as can be seen from FIG. **3**, the separation operation is started from the end portion of the template **23**. For this reason, the end portion of the template **23** is warped. Moreover, the substrate **21** is warped in the vicinity of the end portion of the template **23**. Hereinafter, an explanation will be made considering the case where the end portion of the template **23** is warped.

As depicted in FIG. **4**, when the template **23** is further left up by a fixed force, the separation operation shifts from the end portion of the template **23** toward the center portion thereof. Therefore, the warp of the template **23** proceeds from the end portion toward the center portion.

As seen from FIG. **5**, when the template **23** is further left up, a separation operation of the center portion, that is, the interchip area **25** is started. Micro-patterns do not exist in the interchip area **25**; for this reason, a contact area of the template **23** with the resist layer **22** is small. As a result, a force required for separating the template becomes small. For this reason, when the template **23** is left up by the same force, a separation velocity rapidly increases. As a result, micro-patterns in the vicinity of the interchip area **25** are torn off by means of the template **23**. As shown in FIG. **6**, the template **23** is separated in a state that the torn-off resist portion is filled in a recess portion of the template **23**.

When the foregoing problem arises, a defect is generated in a part of a resist pattern. Moreover, the next pattern transfer is carried out in the foregoing state that the torn-off portion is filled in a recess portion of the template **23**. As a result, a normal pattern is not transferred, and as a result, a defect is generated in a part of the resist pattern.

FIG. **7** is a graph to explain a change according to a condition of a separation force and a separation velocity in the separation operation shown in FIGS. **2** to **6**. Symbols (a) to (e) shown in FIG. **7** correspond to FIGS. **2** to **6**, respectively. At time of (d) in FIG. **7**, the separation force is rapidly reduced while the separation velocity rapidly increases. As a result, micro-resist patterns in the vicinity of the interchip area **25** are torn off. Therefore, it is important to prevent a rapid change of the separation velocity.

Hereinafter, an embodiment of the present invention will be detailedly described.

FIGS. **8** to **10** are views to explain the basic principle of this embodiment.

FIG. **8** is a view showing a normal template pattern when a template is manufactured based on design data of a pattern (including circuit pattern and mark pattern) to be formed in a semiconductor device. In FIG. **8**, an area **35** having no pattern is provided adjacent to an area **31** having a dense pattern **41**. For example, the area **31** is included in the chip area, and the area **35** is included in the interchip area. In this case, the dense pattern exists in the area **31**; therefore, a contact area of a template with a resist layer is very large. Conversely, the area **35** has no pattern; for this reason, a contact area of a template with a resist layer is small. Therefore, when the template is separated from the resist layer, a separation velocity rapidly increases when a separation area shifts from the area **31** to the area **35**. For this reason, there is the possibility that a resist pattern is torn off at the end portion of the area **31**.

In order to solve the foregoing problem, according to this embodiment, as shown in FIGS. **9** (plan view) and **10** (cross-sectional view), the area **32** neighboring the area **31** is provided with a dummy template pattern **42**. Specifically, an area **32** between the area **31** having the dense pattern **41** and the area **33** having no pattern is provided with a dummy template pattern **42**. In this way, it is possible to prevent the foregoing problem. Hereinafter, the explanation will be further made.

A contact area of a template with a resist layer is very large in the area **31** while the contact area of a template with a resist layer is small in the area **35**. For this reason, when a separation area shifts from the area **31** to the area **35**, a separation velocity rapidly increases. Therefore, there is a problem that a contact area rapidly decreases; in other word, there is a problem that a surface area of a template rapidly decreases.

Thus, according to this embodiment, the area **32** adjacent to the area **31** is provided with a dummy template pattern **42** to prevent the surface area of template from rapidly decreasing. Specifically, a ratio of the surface area of the area **32** to an area of the area **32** of the template is set smaller than a ratio of the surface area of the area **31** to an area of the area **31**. In addition, a ratio of the surface area of the area **32** to the area of the area **32** is set larger than a ratio of the surface area of the area **33** to the area of the area **33**. According to this embodiment, a ratio of the surface area of an area A of a template to the area of the area A is called as a surface area ratio. As described above, the dummy template pattern **42** is provided, and thereby, according to the case of FIG. **9**, a change of the surface area ratio is smaller than the case of FIG. **8**.

In this case, the area of the area A means a two-dimensional area (plane area) of the area A, that is, a two-dimensional area (plane area) of a pattern formation surface of a template. The surface area of the area A corresponds to

a contact area of a template with a resist layer, and an area of the side of a template pattern is considered. Namely, the surface area of the area A comes into the total area of the area of the area A and an area of the side of a template pattern formed in the area A. For example, the area of the area A is set as S, the peripheral length of a template pattern formed in the area A is set as L and the depth (height) of a template pattern formed in the area A is set as D. In this case, the surface area of the template pattern formed in the area A is obtained from the following equation.

"Surface area=S+L×D"

The dummy template pattern is generated at design stage before a template is actually prepared and arranged at a placement area of a dummy template pattern.

According to the foregoing embodiment, areas **33** and **35** have no pattern. However, a pattern may be formed in areas **33** and **35** so long as the foregoing relationship is established between the surface area ratios of areas **31**, **32** and **33**. If a large pattern exists in the placement area of the dummy template pattern, the large pattern may be divided so that a dummy template pattern is generated.

As described above, the area **32** provided with a dummy template pattern is interposed between the area **31** having a large surface area ratio and the area **33** having a small surface area ratio. In this way, the surface area ratio of the area **32** is set to a value ranging between the surface area ratio of the area **31** and that of the area **33**. In the manner described above, each surface area ratio of areas **31**, **32** and **33** is set, and thereby, this serves to prevent a rapid change of a surface area ratio, and to prevent a rapid change of a contact area of a template with a resist layer. Therefore, it is possible to prevent a separation velocity from rapidly increasing, and to prevent a resist pattern from being torn off.

Hereinafter, a method of designing the foregoing template pattern will be described with reference to a flowchart shown in FIG. **11**.

First, a template pattern is generated based on the design pattern data of a semiconductor device. Thereafter, the generated template pattern is divided into a plurality of mesh-shaped areas (S**11**).

A surface area ratio of each divided area is calculated, and then, a surface area ratio map is prepared (S**12**).

Based on the foregoing surface area ratio map, an area of arranging a dummy template pattern is determined (S**13**). Specifically, a divided area having a rapidly decreased surface area ratio with respect to neighboring divided area is obtained, and then, the foregoing divided area is determined as a placement area of a dummy template pattern.

A surface area ratio of each divided area adjacent to both sides of the placement area of a dummy template pattern is calculated based on the design pattern data (S**14**).

A dummy template pattern to be arranged in the dummy template pattern placement area is generated (S**15**). Specifically, based on the surface area ratios of both neighboring divided areas calculated in step S**14**, a dummy template pattern is generated so that a surface area ratio of the dummy template pattern placement area is set to a value ranging between the surface area ratios of both neighboring divided areas.

According to this embodiment, a third area between a first area having a large surface area ratio (first surface area ratio) and a second area having a small surface area ratio (second surface area ratio) is provided with a dummy template pattern. In this way, a surface area ratio (third surface area ratio) of the third area is set smaller than the first surface area ratio and larger than the second surface area ratio. This serves to prevent a rapid change of a surface area ratio, and to prevent a rapid change of a contact area of a template with a resist layer. Therefore, it is possible to prevent a rapid increase of a separation velocity, and to effectively prevent a resist pattern from being torn off. As a result, the generation of a defect can be prevented in the resist pattern.

Various changes may be made with respect to the dummy template pattern. Hereinafter, various modifications will be described.

FIG. **12** is a view schematically showing a first modification example. According to the embodiment shown in FIGS. **9** and **10**, the area **32** is provided with the dummy template pattern **42** having a pitch larger than the template pattern **41** of the area **31**. In this way, the number of patterns of the area **32** is relatively reduced, and the surface area ratio of the area **32** is set smaller than that of the area **31**. According to this modification example, an area **32** is provided with a dummy template pattern **42** having a size (pattern width) larger than a template pattern **41** of an area **31**. In this way, the number of patterns of the area **32** is relatively reduced, and the surface area ratio of the area **32** is set smaller than that of the area **31**. Therefore, according to this modification example, the same effect as described above is obtained.

FIG. **13** is a view schematically showing a second modification example. According to the embodiment shown in FIGS. **9** and **10**, the template pattern **41** of the area **31** is a line-shaped pattern, and the dummy template pattern **42** of the area **32** is a line-shaped pattern. According to the second modification example, a template pattern **41** of an area **31** is a square-shaped pattern, and also, a dummy template pattern **42** of an area **32** is a square-shaped pattern. According to this modification example, the area **32** is provided with a dummy template pattern **42** having a pitch larger than the template pattern **41** of the area **31**. In this way, the number of patterns of the area **32** is relatively reduced, and the surface area ratio of the area **32** is set smaller than that of the area **31**. Therefore, according to this modification example, the same effect as described above is obtained.

FIG. **14** is a view schematically showing a third modification example. According to the third modification example, a dummy template pattern **42** of an area **32** is a square-shaped pattern as well as the second modification example. According to this modification example, the area **32** is provided with a dummy template pattern **42** having a size larger than a template pattern **41** of an area **31**. In this way, the number of patterns of the area **32** is relatively reduced, and a surface area ratio of the area **32** is smaller than that of the area **31**. Therefore, according to this modification example, the same effect described above is obtained.

FIG. **15** is a view schematically showing a fourth modification example. According to the embodiment shown in FIGS. **9** and **10**, the surface area ratio of the template becomes small in the order of areas **31**, **32** and **33**. According to the fourth modification example, the surface area ratios of areas **31** and **33** are relatively large while the surface area ratio of the area **32** ranging between areas **31** and **33** is relatively small. Even if the foregoing configuration is employed, it is possible to prevent a defect from being generated in a resist pattern.

FIG. **16** is a view schematically showing a fifth modification example. According to the embodiment shown in FIGS. **9** and **10**, the surface area ratio of the area **32** provided with the dummy template pattern **42** is constant. According to the fifth modification example, the surface area ratio

changes in the area **32**. A change of the surface area ratio is given at least two stages or more. Specifically, the area **32** is divided into two sub-areas or more, and one sub-area relatively positioning on the side of the area **31** is set as a sub-area S**1**. Further, one sub-area (i.e., sub-area ranging between the area **33** and the sub-area S**1**) relatively positioning on the side of the area **33** is set as S**2**. In this case, a surface area ratio of the sub-area S**1** is smaller than that of the area **31**. A surface area ratio of the sub-area S**2** is smaller than that of the area sub-area S**1** and larger than that of the area **33**. According to this example shown in FIG. **16**, in the area **32**, the surface area ratio gradually decreases from the area **31** toward the area **33**. For example, preferably, a dummy template pattern **42** is provided so that a change of the surface area ratio is constant. According to this modification example, the same effect as described above is obtained. In addition, according to this example, the surface area ratio gradually changes in the area **32**; therefore, this serves to further prevent a rapid change of a separation velocity.

A method of manufacturing a template based on the template pattern designed according to the foregoing embodiments and a method of manufacturing a semiconductor device will be described below with reference to a flowchart shown in FIG. **17**.

First, template pattern data designed according to the foregoing embodiments is prepared (S**21**). Based on the prepared template pattern data, the surface of a template substrate (quartz substrate) is formed with a template pattern by means of electron beam (EB) exposure and etching, and thus, a template is manufactured (S**22**). A semiconductor device (semiconductor integrated circuit device) is manufactured using the foregoing template thus manufactured. Specifically, the template pattern formed on the template is transferred to a resist layer (imprint material layer) on a substrate so that a resist pattern is formed (S**23**). Further, etching is carried out using the formed resist pattern as a mask so that a desired pattern is formed on a substrate (S**24**).

The foregoing method is employed, and thereby, it is possible to improve the manufacture yield of a semiconductor device. In other words, when the template pattern is transferred to the resist layer on the substrate, it is possible to prevent a defect from being generated in the resist pattern. Therefore, this contributes to improving the manufacture yield of a semiconductor device.

Moreover, the method of designing a template pattern described in the foregoing embodiment is realizable using a computer whose operation is controlled according to a program stored with the procedures of the foregoing method. The foregoing program is provided using a recoding medium such as a magnetic disk or a communication line (wire or wireless line) such as Internet.

The following is an explanation of the verification result (measurement result) when a pattern is actually formed on a substrate using the template obtained according to the method of the embodiment.

FIG. **18** is a view showing a template used for verification. In the template, a line and space pattern (L/S pattern, half pitch=80 nm, line width:space width=L:S=1:1) is used as an evaluation pattern, and the L/S pattern is arranged on each of areas A to I. Further, a dot pattern shown in FIG. **19** is used as a dummy pattern. Specifically, three dummy patterns having pattern covering ratios (pattern occupation ration) 70%, 35% and 0% (no dummy pattern) are used. The relationship between a peripheral pattern covering ratio of an evaluation pattern (L/S pattern) and a defect density (DD) after a template is separated is investigated using the verification pattern. An average pattern covering ratio of areas having a width 50 μm shown by the slanted line of FIG. **20** was used as a peripheral pattern covering ratio of an evaluation pattern.

FIG. **21** is a graph showing the measured result. An approximate expression (straight line) was obtained from the measured result, and further, a peripheral pattern covering ratio to a defect density (DD) was calculated. As a result, a pattern covering ratio at DD=10/cm^2 was 44.6%, a pattern covering ratio at DD=1/cm^2 was 46.8%, and further, a pattern covering ratio at DD=0.1/cm^2 was 47.1%. Therefore, in order to obtain DD$<$1/cm^2, the pattern covering ratio must be set to about 47% or more. In other words, it is desirable that a peripheral pattern covering ratio is set to about 47% or more in order to obtain DD$<$1/cm^2 in an L/S pattern of L:S=1:1 (pattern covering ratio: 50%). FIG. **22** is a graph showing a value (100/surface area ratio (%)) expressed using the foregoing defined surface area ratio (surface area/area) as the horizontal axis.

Additional advantages and modifications will readily occur to those skilled in the art. Therefore, the invention in its broader aspects is not limited to the specific details and representative embodiments shown and described herein. Accordingly, various modifications may be made without departing from the spirit or scope of the general inventive concept as defined by the appended claims and their equivalents.

What is claimed is:

1. A computer-implemented method of designing a template pattern used for imprint lithography, comprising:

determining, by a computer, a first area, a second area, and a third area where a dummy template pattern is to be formed, the third area being between and adjacent to the first area and the second area of a template;

generating, by **[**a**]** *the* computer, data of **[**a**]** *the* dummy template pattern to be formed in **[**a**]** *the* third area **[**between first and second areas of a template**]** based on data of a design pattern of the template,

the data of the dummy template pattern being generated so that a third surface area ratio showing a ratio of a surface area of the third area to an area of the third area is set to be:

smaller than a first surface area ratio showing a ratio of a surface area of the first area to an area of the first area, and

larger than a second surface area ratio showing a ratio of a surface area of the second area to an area of the second area.

2. The method according to claim **1**, wherein generating the data of the dummy template pattern includes:

calculating the first surface area ratio based on the data of the design pattern;

calculating the second surface area ratio based on the data of the design pattern; and

generating the data of the dummy template pattern based on the first and second surface area ratios.

3. The method according to claim **1**, wherein the first area is included in a chip area.

4. The method according to claim **1**, wherein the second area is included in an interchip area.

5. The method according to claim **1**, wherein the second area has no pattern.

6. The method according to claim **1**, wherein a pitch **[**of**]** *between* a dummy template pattern of the third area is larger than **[**that**]** *a width* of a *dummy* template pattern of the **[**first**]** *third* area.

7. The method according to claim **1**, wherein a width of a dummy template pattern of the third area is larger than that of a template pattern of the first area.

8. The method according to claim **1**, wherein the surface area ratio of the third area is constant.

9. The method according to claim **1**, wherein the surface area ratio of the third area changes.

10. The method according to claim **1**, wherein the third area includes a first sub-area and a second sub-area between the second area and the first sub-area, and

a fourth surface area ratio showing a ratio of a surface area of the first sub-area to an area of the first sub-area is smaller than the first surface area ratio, and

a fifth surface area ratio showing a ratio of a surface area of the second sub-area to an area of the second sub-area is smaller than the fourth surface area ratio, and larger than the second surface area ratio.

11. The method according to claim **1**, wherein the surface area ratio of the third area decreases from the first area toward the second area.

12. A method of manufacturing a template, comprising:

forming a template pattern designed using the method according to claim **1** in a template substrate.

13. A method of manufacturing a semiconductor device, comprising:

transferring a pattern formed in the template manufactured using the method according to claim **12** to an imprint material layer on a substrate.

14. A computer-implemented method of designing one or more template patterns used for imprint lithography, comprising:

determining, by a computer, an area of a first region, an area of a second region, and an area of a third region where a template pattern is to be formed, the third region being between and adjacent to the first region and the second region of a template;

generating, by the computer, data of the template pattern to be formed in the third region based on data of a design pattern of the template;

wherein the first region, the second region, and the third region are associated respectively with a first surface area ratio, a second surface area ratio, and a third surface area ratio;

and wherein the third surface area ratio is smaller than the first surface area ratio and larger than the second surface area ratio,

wherein the first region is included in a chip area, and the second region is included in an interchip area between the chip area and another chip area, and the third region is included in the interchip area.

15. The method of claim 14, wherein generating the data of the template pattern includes:

calculating the first surface area ratio and the second surface area ratio after determining the area of the first region, the area of the second region, and the area of the third region; and

determining the template pattern of the third region based on the calculated first surface area ratio and the calculated second surface area ratio.

16. The method of claim 14, wherein the first region is included in a chip area.

17. The method of claim 14, wherein the second region and the third region are included in an interchip area.

18. The method of claim 14, wherein the second region has no pattern.

19. The method according to claim 14, wherein a third pitch between the template pattern to be formed in the third region is larger than a first pitch between a template pattern of the first region.

20. The method according to claim 14, wherein a third width of the template pattern to be formed in the third region is larger than a first width of a template pattern of the first region.

21. The method according to claim 14, wherein the template pattern to be formed in the third region includes a first sub-region and a second sub-region; wherein the first sub-region is associated with a first sub-region surface area ratio; wherein the second sub-region is associated with a second sub-region surface area ratio; wherein the first sub-region surface area ratio is different from the second sub-region surface area ratio.

22. The method according to claim 21, wherein the second sub-region is to be formed between the second region and the first sub-region; wherein the first sub-region surface area ratio is smaller than the first surface area ratio; and wherein the second sub-region surface area ratio is smaller than the first sub-region surface area ratio.

23. The method according to claim 22, wherein the second sub-region surface area ratio is larger than the second surface area ratio.

24. The method according to claim 14, wherein the template pattern to be formed in the third region includes a dummy template pattern.

25. A method of manufacturing a template, comprising:

forming at least one of the one or more template patterns designed using the method of claim 14 in a template substrate.

26. A method of manufacturing a semiconductor device, comprising:

transferring one or more patterns formed in the template manufactured using the method according to claim 25 to an imprint material layer on a substrate.

27. A computer-implemented method of designing one or more template patterns used for imprint lithography, comprising:

determining, by a computer, an area of a first region, an area of a second region, and an area of a third region where a template pattern is to be formed, the third region being between and adjacent to the first region and the second region of a template;

generating, by the computer, data of the template pattern to be formed in the third region based on data of the design pattern of the template;

wherein the first region, the second region, and the template pattern to be formed in the third region are associated respectively with a first density, a second density, and a third density; and

wherein the third density is smaller than the first density and larger than the second density.

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